2mmx5mm RECTANGULAR SOLID LAMP

Part Number: L-103EDT

Orange

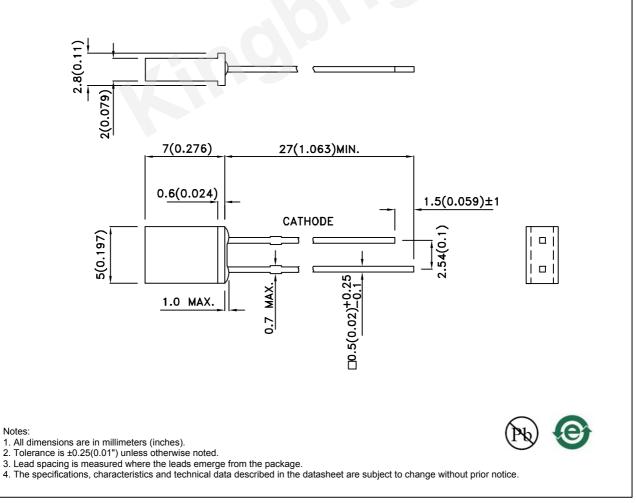
Features

- Low power consumption.
- Reliable and rugged.
- Excellent uniformity of light output.
- Suitable for level indicator.
- Long life solid state reliability.
- RoHS compliant.

Description

The Orange source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



SPEC NO: DSAE2440 APPROVED: WYNEC REV NO: V.9A CHECKED: Allen Liu DATE: MAY/09/2013 DRAWN: Q.M.Chen PAGE: 1 OF 6 ERP: 1101000365

Selection Guide

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
	Orange (GaAsP/GaP)	Orange Diffused	4	8	• 110°
L-103EDT			*1.2	*3	

Notes:

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Orange	627		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Orange	617		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Orange	45		nm	I⊧=20mA
С	Capacitance	Orange	15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Orange	2	2.5	V	l⊧=20mA
lr	Reverse Current	Orange		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

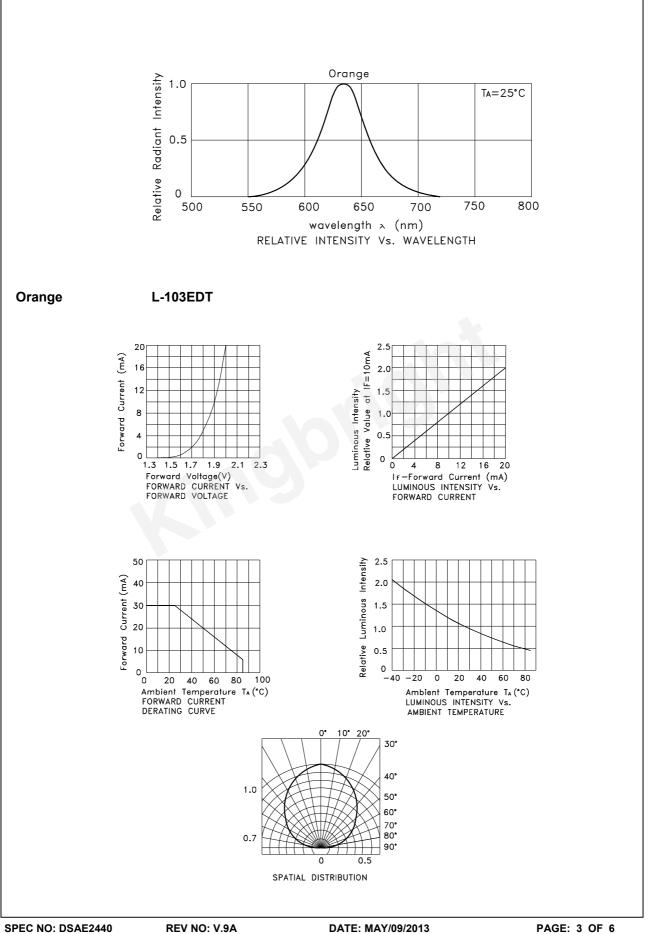
Parameter	Orange	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	160	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

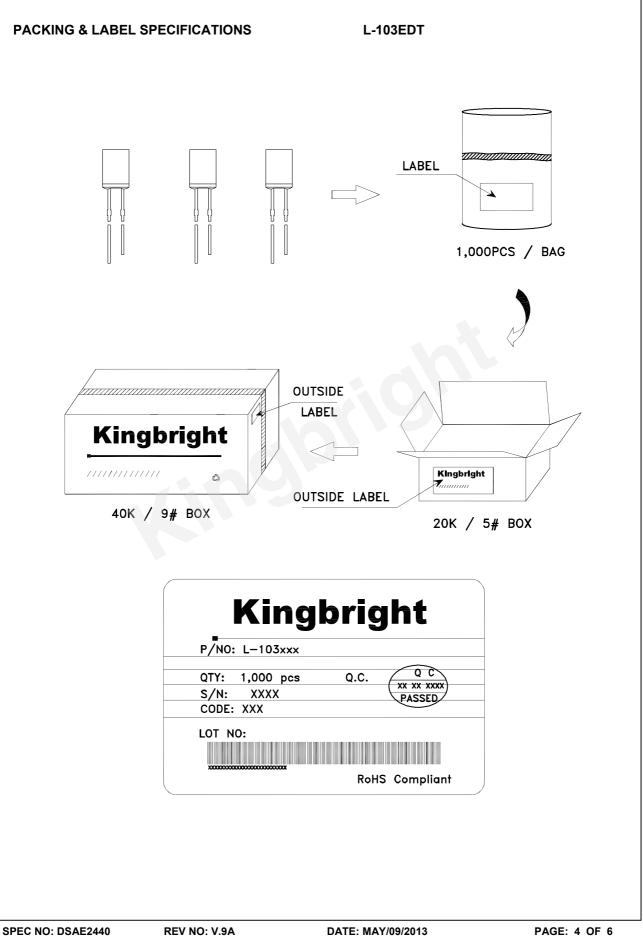
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

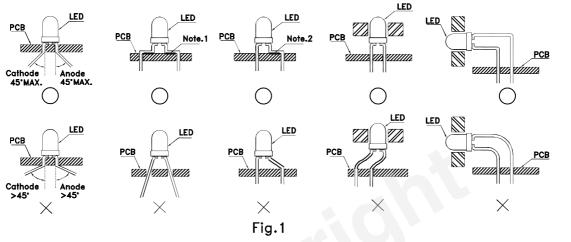
3. 5mm below package base.





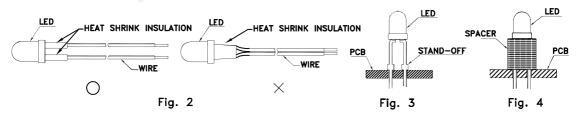
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

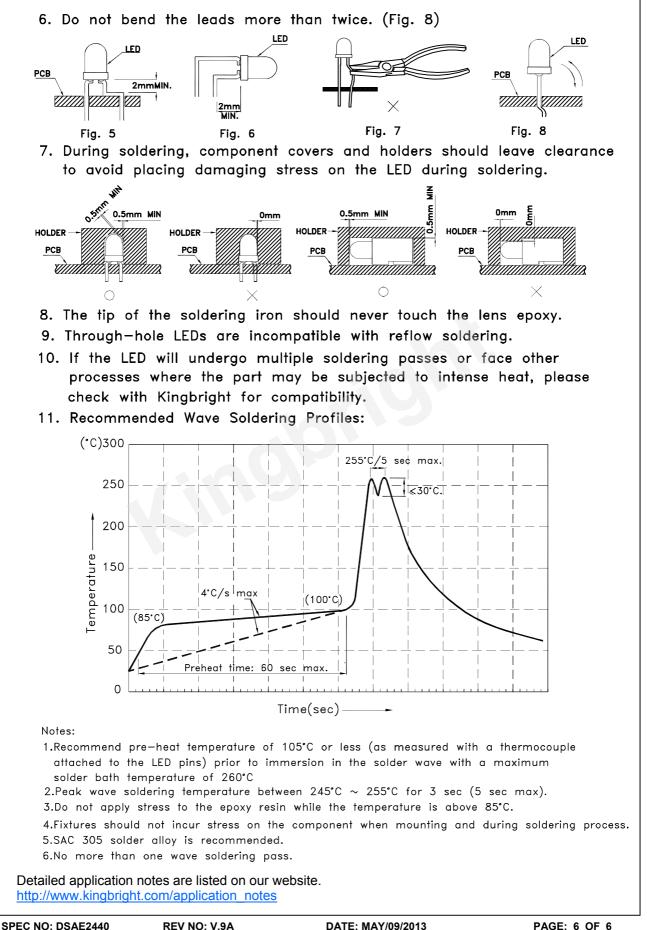


" \bigcirc " Correct mounting method "imes" Incorrect mounting method

- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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